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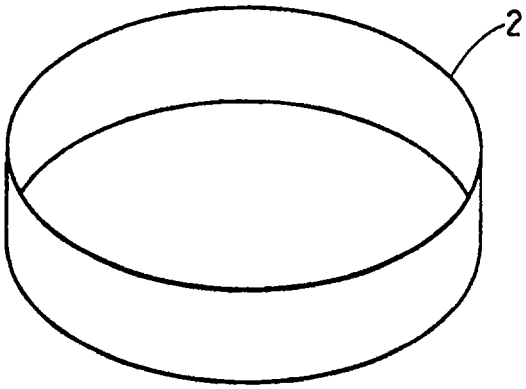
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(54) Title: RESIN MOLDED ARTICLE FOR CHAMBER LINER

(57) Abstract

A resin molded article for fitting to an inside wall of a liner in a chamber of a dry etching apparatus used in semiconductor manufacture is disclosed. The resin molded article is a seamless annular molded article having a heat resistance temperature of at least 100 °C, a tensile elongation at break of at least 0.3 %, a flexural modulus of at least 10,000 kg/cm^2, an outside diameter from 0 to 0.3 % larger than the inside diameter of the liner, and a wall thickness of not more than 2 mm.



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